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## VLSI Design (BEC-41) (Unit-1, Lecture-6)



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## **Introduction**

- The SPICE software that was distributed by UC Berkeley beginning in the late 1970s had three built-in MOSFET models
  - LEVEL1(MOS1) is a described y a square-law current-voltage characteristics
  - LEVEL2 (MOS2) is a detailed analytical MOSFET model
  - LEVEL 3 (MOS3) is a semi-empirical model
    - Both MOS2 and MOS3 include second-order effects
      - The short channel threshold voltage, subthreshold conduction, scattering-limited velocity saturation, and charge-controlled capacitances
  - The BSIM3 version
    - More accurate characterization sub-micron MOSFET characteristics



### **Basic concept**

 The equivalent circuit structure of the NMOS LEVEL 1 model







## The LEVEL 1 model equation

Linear region

$$I_{D} = \frac{k'}{2} \cdot \frac{W}{L_{eff}} \cdot \left[2 \cdot \left(V_{GS} - V_{T}\right)V_{DS} - V_{DS}^{2}\right] \cdot \left(1 + \lambda \cdot V_{DS}\right) for \quad V_{GS} \ge V_{T}$$

and  $V_{DS} < V_{GS} - V_T$  •  $\lambda = 0$ 

Saturation region

$$I_{D} = \frac{k'}{2} \cdot \frac{W}{L_{eff}} \cdot (V_{GS} - V_{T})^{2} \cdot (1 + \lambda \cdot V_{DS}) for \quad V_{GS} \ge V_{T}$$

and  $V_{DS} \ge V_{GS} - V_T$ 

The threshold voltage

$$\begin{split} V_T &= V_{T0} + \gamma \cdot \left( \sqrt{\left| 2\phi_F \right| + V_{SB}} - \sqrt{\left| 2\phi_F \right|} \right) \\ L_{eff} &= L - 2 \cdot L_D \end{split}$$

$$k' = \mu \cdot C_{ox} \text{ where } C_{ox} = \frac{\varepsilon_{ox}}{t_{ox}}$$
$$\gamma = \frac{\sqrt{2 \cdot \varepsilon_{Si} \cdot q \cdot N_A}}{C_{ox}}$$
$$2\phi_F = 2\frac{kT}{q} \cdot \ln\left(\frac{n_i}{N_A}\right)$$

- K'=27.6μA/V² KP=27.6U •
- V<sub>T0</sub>=1.0V •
- γ=0.53V<sup>1/2</sup>
- 2∲F=-0.58
- μ<sub>n</sub>=800cm²/Vs
- t<sub>ox</sub>=100nm
- N<sub>A</sub>=10<sup>15</sup>cm<sup>-3</sup> NSUB=1E15
- L<sub>D</sub>=0.8µm

VTO=1

- **GAMMA=0.53**
- PHI=0.58
- LAMBDA=0
- UO=800
  - TOX=100E-9

  - LD=0.8E-6



#### Variation of the drain current with model parameter



Figure 4.2 Variation of the drain current with model parameter VTO, for the LEVEL 1 model. (Copyright © 1988 by McGraw-Hill, Inc.)



Figure 4.4 Variation of the drain current with model parameter TOX, for the LEVEL 1 model. (Copyright © 1988 by McGraw-Hill, Inc.)



Figure 4.3 Variation of the drain current with model parameter KP, for the LEVEL 1 model. (Copyright © 1988 by McGraw-Hill, Inc.)



Figure 4.5 Variation of the drain current with parameter LAMBDA, for the LEVEL 1 model. (Copyright © 1988 by McGraw-Hill, Inc.)



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### The LEVEL 2 model equation

$$I_{D} = \frac{k'}{(1 - \lambda \cdot V_{DS})} \cdot \frac{W}{L_{eff}} \cdot \left\{ \left( V_{GS} - V_{FB} - \left| 2\phi_{F} \right| - \frac{V_{DS}}{2} \right) \cdot V_{DS} - \frac{2}{3} \cdot \gamma \cdot \left[ \left( V_{DS} - V_{BS} + \left| 2\phi_{F} \right| \right)^{3/2} - \left( -V_{BS} + \left| 2\phi_{F} \right| \right)^{3/2} \right] \right\}$$

The saturation voltage

$$V_{DSAT} = V_{GS} - V_{FB} - |2\phi_F| + \gamma^2 \cdot \left(1 - \sqrt{1 + \frac{2}{\gamma^2} \cdot (V_{GS} - V_{FB})}\right)$$

The saturation mode current

$$I_D = I_{Dsat} \cdot \frac{1}{\left(1 - \lambda \cdot V_{DS}\right)}$$

The zero bias threshold voltage

$$V_{T0} = \Phi_{GC} - \frac{q \cdot N_{ss}}{C_{ox}} + \left| 2\phi_F \right| + \gamma \sqrt{\left| 2\phi_F \right|}$$

- In the current equation above, the surface carrier mobility has been assumed constant, and its variation with applied terminal voltages has been neglected
- In reality, the surface mobility decreases with the increasing gate voltage
  - Due to the scattering of carriers in the channel

$$k'_{(new)} = k' \cdot \left(\frac{\varepsilon_{Si}}{\varepsilon_{ox}} \cdot \frac{t_{oc} \cdot U_{c}}{(V_{GS} - V_{T} - U_{t} \cdot V_{DS})}\right)^{Ue}$$

 $U_c$  is the gate - to - channel critical field

 $U_t$  is the contribution of the drain voltage to the gate - to - channel field

 $U_e$  is the exponential fitting parameter



#### variation of channel length in saturation mode

$$\dot{L}_{eff} = L_{eff} - \Delta L$$
  
$$\Delta L = \sqrt{\frac{2 \cdot \varepsilon_{Si}}{q \cdot N_A}} \cdot \left[\frac{V_{DS} - V_{DSAT}}{4} + \sqrt{1 + \left(\frac{V_{DS} - V_{DSAT}}{4}\right)^2}\right]$$

The empirical channel length shortening coefficient

$$\lambda = \frac{\Delta L}{L_{eff} \cdot V_{DS}}$$

The slope of the  $I_D - V_{DS}$  vurve is saturation can be adjusted and fitted to experimental data by changing the substrate doping parameter  $N_A$ In this case, however, other  $N_A$  - dependent electrical parameters such as  $2\phi_F$  and  $\gamma$  must be specified separately in the .MODEL statement



## **Saturation of carrier velocity**

- The calculation of the saturation voltage  $V_{\text{DSAT}}$  is based on the assumption
  - The channel charge near the drain becomes equal to zero when the device enters saturation
  - This hypothesis is actually incorrect
    - Since a minimum charge concentration greater than zero must exist in the channel, due to the carriers that sustain the saturation current
    - The minimum concentration depends on the speed of the carriers
    - The inversion layer charge at the channel-end is found as

$$Q_{inv} = \frac{I_{Dsat}}{W \cdot v_{max}}$$

$$\Delta L = X_D \cdot \sqrt{\left(\frac{X_D \cdot v_{max}}{2 \cdot \mu}\right)^2 + V_{DS} - V_{DSAT}} - \frac{X_D^2 \cdot v_{max}}{2 \cdot \mu}$$

$$X_D = \sqrt{\frac{2 \cdot \varepsilon_{Si}}{q \cdot N_A \cdot N_{eff}}}$$

– The parameter  $\rm N_{eff}$  is used as a fitting parameter



## Subthreshold conduction

- For  $V_{GS} < V_T$ , there is a channel current even when the surface is not in strong inversion
- This subthreshold current
  - Due mainly to diffusion between and the channel
  - Becoming an increasing concern for deepsub-micron designs
- The model implemented in SPICE introduces an exponential, semi-empirical dependence of the drain current on V<sub>GS</sub> in the *weak inversion region*

-  

$$I_D$$
 (weak inversion) =  $I_{on} \cdot e^{(V_{GS} - V_{on}) \cdot \left(\frac{q}{nkT}\right)}$ 

 $I_{on}$  is the current in strong inversion for  $V_{GS} = V_{on}$ the voltage  $V_{on}$  is found as

$$V_{on} = V_T + \frac{nkT}{q} \text{ where } n = 1 + \frac{q \cdot N_{FS}}{C_{ox}} + \frac{C_d}{C_{ox}}$$



**Figure 4.7** Variation of the drain current in the weak inversion region, as a function of the gate voltage and for different values of the parameter  $N_{FS}$ , in the LEVEL 2 model. (*Copyright* © 1988 by McGraw-Hill, Inc.)

The parameter  $N_{FS}$  is defined as the number of fast superficial states and is used as a fitting parameter that determines the slope of the subthreshold current - voltage characteristics

 $C_d$ : is the depletion capacitance

This model introduces a discontinuity for  $V_{GS} = V_{on}$ , therefore, the simulation

of the transition region between weak and strong inversion is not very precise



## The LEVEL 3 model equations

- The LEVEL 3 model has been developed for simulation of short channel MOS transistor
  - Quite precisely for channel lengths down to  $2\mu m$
  - The current-voltage equation in the linear region has been simplified with a Taylor series expansion
  - The majority of the LEVEL 3 model equations are empirical
    - To improve the accuracy of the model
    - To limit the complexity of the calculation

$$I_D = \mu_s \cdot C_{ox} \cdot \frac{W}{L_{eff}} \cdot \left( V_{GS} - V_T - \frac{1 + F_B}{2} \cdot V_{DS} \right) \cdot V_{DS}$$

where 
$$F_B = \frac{\gamma \cdot F_s}{4 \cdot \sqrt{\left|2\phi_F\right| + V_{SB}}} + F_n$$

The empirical parameter  $F_B$  express the dependence of the bulk depletion charge The  $V_T$ .  $F_s$ , and  $\mu_s$  are influenced by the short - channel effects

The  $F_n$  is influenced by the narrow - channel effects

$$\mu_s = \frac{\mu}{1 + \theta \cdot \left( V_{GS} - V_T \right)}$$

The decrease in the effective mobility with the average lateral electrical field

$$\mu_{eff} = \frac{\mu_s}{1 + \mu_s \cdot \frac{V_{DS}}{v_{max} \cdot L_{eff}}}$$



## State-of-art MOSFET models

- BSIM-Berkeley short-channel IGFET model
  - The model is analytically simple and is based on a small number of parameters, which are normally extracted from experimental data
  - Accuracy and d\efficiency
  - Widely used by many companies and silicon foundries
- EKV (Enz-Krummenacher-Vittoz) transistor model
  - Previous models considering
    - The strong-inversion region of operation separately from the weakinversion region
    - Causing serous problems in the modeling of transistors at very low voltages as in many cases involving deep sub-micron CMOS technology
  - Attempting to solve this problem by
    - Using a unified view of the transistor operating regions
    - Avoiding the use of disjoint equations in strong and weak inversion



### Gate oxide capacitance

- SPICE uses a simple gate oxide capacitance model that represents the charge storage effect by three nonlinear two-terminal capacitor: C<sub>GB</sub>, C<sub>GS</sub> and C<sub>GD</sub>
- The geometry information required for the calculation of gate oxide capacitance are:
  - Gate oxide thickness TOX
  - Channel width W
  - Channel length L
  - Lateral diffusion LD
- The capacitances CGBO, CGSO, and CGDO, which are specified in the .MODEL statement, are the overlap capacitances between the gate and the other terminals outside the channel region
- If the parameter XQC is specified in the .MODEL statement
  - SPICE uses a simplified version of the charge-controlled capacitance model proposed by Ward



**Figure 4.8** Oxide capacitances as functions of the gate-to-substrate voltage, according to Ward's capacitance model. *(Copyright © 1988 by McGraw-Hill, Inc.)* 

## **Junction capacitance**

$$C_{SB} = \frac{C_j \cdot AS}{\left(1 - \frac{V_{BS}}{\phi_0}\right)^{M_j}} + \frac{C_{jsw} \cdot PS}{\left(1 - \frac{V_{BS}}{\phi_0}\right)^{M_{jsw}}}$$
$$C_{DB} = \frac{C_j \cdot AD}{\left(1 - \frac{V_{BD}}{\phi_0}\right)^{M_j}} + \frac{C_{jsw} \cdot PD}{\left(1 - \frac{V_{BD}}{\phi_0}\right)^{M_{jsw}}}$$

 $C_j$ : the zero - bias depletion capacitance per unit area at the bottom of the junction  $C_{jsw}$ : the zero - bias depletion capzcitance per unit length at the sidewall junctions  $C_{jsw} \cong \sqrt{10} \cdot C_j \cdot x_j$ 

AS and AD are the source and the drain areas

PS and PD are the source and the drain perimeters

 $M_j$  and  $M_{jsw}$  denote the junction grading coefficients for the bottom and the sidewalls junctions Default values are  $M_j = 0.5$  and  $M_{jsw} = 0.33$ 



# Comparison of the SPICE MOSFET models

- The LEVEL 1 model
  - Not very precise
  - Quick and rough estimate of the circuit performance without much accuracy
- THE LEVEL 2 model
  - Require a larger time
  - May occasionally cause convergence problems in the Newton-Raphson algorithm used in SPICE
- THE LEVEL 3 model
  - The CPU time needed for model evaluation is less and the number of iterations are significantly fewer for the LEVEL three model
  - Disadvantage
    - The complexity of calculating some of its parameters

